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Docket No.: 80422(302761)
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Kunihiro Kakihara et al.

Application No.: 10/562,007

Confirmation No.: 1070

Filed: December 23, 2005

Art Unit: 1794

For: HEAT-TREATED RESIN MOLDINGS AND
HEAT-TREATING APPARATUS FOR SOME

Examiner: J. C. Yager

RESPONSE TO RESTRICTION REQUIREMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the restriction requirement set forth in the Office Action mailed July 1, 2008, between:

Group I, claims 1,3, 5-7 and 15-19, drawn to a heat-treated resin molding.

Group II, claims 8-14 and 20, drawn to a resin molding heat-treating apparatus.

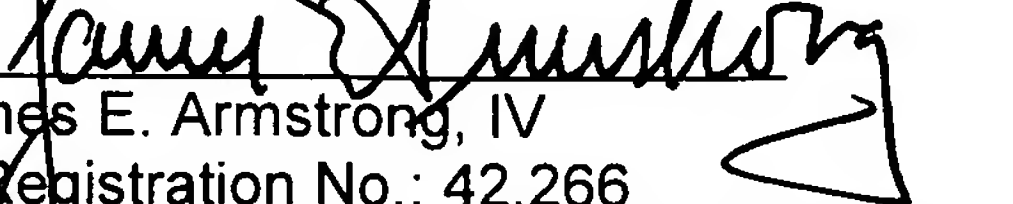
Applicant hereby elects Group II, claims 8-14 and 20, drawn to a resin molding heat-treating apparatus, without traverse.

In any event, Applicant reserves the right to file one or more divisional applications directed to the non-elected claims prior to issuance of any patent maturing from the instant application.

Please charge this fee and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

Respectfully submitted,

Dated: July 14, 2008

By 
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